

Part of the Teledyne Imaging Group

LINCE1M3 CMOS SENSOR L13M1V0N B&W

Lince1M3, Achieving 980fps with 1.3MP Resolution



Lince1M3 is a CMOS digital image sensor optimized for medical, Intelligent Transportation Systems (ITS) and industrial machine vision applications requiring high-speed. The sensor incorporates a sophisticated readout channel with a high-accuracy 12-bit ADC to deliver the best quality images under any illumination condition.

The exposure and read-out timings are generated by a complex control-unit that enables a wide variety of operational modes. Trigger management is specially designed for those industrial applications demanding ultra-low trigger-to-exposure latency.

SENSOR FEATURES

1.3 Megapixel resolution with a 1,244 x 1,024 pixel array

High-performance global shutter pixel for blur-free images **Ultra-high speed of 980fps** at full frame & 12 bits

Embedded features to increase frame rate and dynamic range (ROI, binning, HDR, subsampling)

CUSTOMER BENEFITS

Upgrade your inspection system throughput with superior frame rate

Improve your production yields with higher contrast images and better defect classification **Perfect your slow-motion capture** with highly dynamic and blur-free images

Deliver the best quality images under **any illumination condition**



imaging.teledyne-e2v.com

FIND OUT MORE!

SENSOR CHARACTERISTICS

PARAMETER	LINCE1M3
Resolution – pixels	1,244 (H) x 1,024 (V)
Pixel size -square	10µm
Shutter type	Global shutter
Size type – inch	1
Frame rate @12bits	980fps @ full-frame 1,925fps @ 1,244 x 512 3,710fps @ 1,244 x 256
Bit depth	8 - 10 - 12
SNR _{max} – dB	39.8
Dynamic range – dB	58 (standard mode) up to 100 (HDR mode)
Sensitivity – V/lux.s	14.4
Power consumption	≤2W @max frame rate

KEY ELEMENTS

- » 1.3 Megapixel resolution
- 10µm global shutter pixel enabling exposure during readout
- » C-mount compatible (16.39mm diagonal)
- » Ceramic LGA package, 28 x 28mm², 181 pins
- » Pin-to-pin and optical compatible with Lince5M
- » 24 LVDS ports (scalable down to 4) providing a speed up to 16.6Gbps
- » SPI control
- » Power down capability for very low power dissipation

EMBEDDED FEATURES

- » High Dynamic Range (HDR)
- » Region of Interest (ROI)
- » Vertical binning
- » Sub sampling
- » Horizontal blanking

TYPICAL APPLICATIONS

- » Machine vision
- » Robotics
- » Intelligent Transportation Systems (ITS)
- » Medical
- » Slow-motion